

first and second tuners are electrically shielded from each other by a grounding conductor layer provided within the multi-layer board.

3. (Amended) The digital broadcast receiving tuner according to Claim 2, wherein the first and second tuners each comprise a high-frequency unit and a demodulation unit, and wherein the high-frequency unit of the first tuner and the demodulation unit of the second tuner are arranged at a first position, and the demodulation unit of the first tuner and the high-frequency unit of the second tuner are arranged at a second position, the first and second positions being opposite to each other with the multi-layer board interposed therebetween.

4. (Amended) The digital broadcast receiving tuner according to Claim 3, wherein the multi-layer board comprises at least the two grounding conductor layers between lamination layers, each grounding conductive layer ^{has} ~~deletion~~ units and a ~~first remainder, the deletion units of a first grounding conductive layer more~~ proximate to a particular high-frequency unit of one of the first and second tuners than a second grounding conductive layer are arranged more proximate to the ~~particular high-frequency unit than the first remainder of the one of the first and second tuners and the first remainder of the first grounding conductive layer is arranged more proximate to a particular demodulation unit of the one of the first and second tuners than the deletion units of the one of the first and second tuners to thereby increase a facing distance between the wiring pattern of the particular high-frequency unit and the corresponding first remainder.~~

5. (Amended) The digital broadcast receiving tuner according to Claim 4, wherein each high-frequency unit comprises an IC component having a direct conversion unit including an oscillator and a mixer, and each grounding conductor layer has a second remainder that opposes a lower portion of the corresponding IC component.

6. (New) The digital broadcast receiving tuner according to Claim 5, wherein the second remainder of each grounding conductor layer is disposed between deletion units of the corresponding grounding conductor layer.